



Transistor Pinout Complete Reference Guide

BJT & MOSFET Pinouts · Multimeter Identification · Part Selection · Assembly Best Practices

1. Package Pinout Overview

The table below summarizes the four most common through-hole and SMD packages. Pin numbers are read with the device front (marked) face toward you and leads pointing downward, left-to-right.

Package	Pin Order (left→right)	Orientation to Read Pins	Notes
TO-92	Varies by part number	Flat face toward you, leads pointing down	Most common small-signal package. No heatsink. Max dissipation ~625 mW. Always verify with datasheet.
SOT-23	Varies; typically: 1(BL) 2(BR) 3(Top)	Dot or chamfer marks Pin 1 on silkscreen	SMD equivalent of TO-92. Pin assignment differs between BJT and MOSFET variants. Confirm datasheet before routing PCB.
TO-220	Varies by part number	Heatsink tab facing away, leads pointing down	Heatsink tab is electrically connected to center pin. Use insulating pad + bushing if mounting to chassis.
TO-92S (wide)	Same as TO-92 for the same part	Flat face toward you, leads pointing down	Wider lead spacing (~2.54 mm). Common in S8050/S8550. Direct mechanical replacement for TO-92.

Critical: Even within the same package, different part numbers may have completely different pin assignments. Always verify against the official datasheet before soldering.

2. Quick Reference Pinout Table — 13 Essential Parts

Pinout shown left-to-right with device front face toward you, leads pointing down. **E** = Emitter **B** = Base **C** = Collector **G** = Gate **D** = Drain **S** = Source

Part No.	Type	Pkg	Pinout (L→R)	Complement / Alt	Key Specs	Notes
2N3904	NPN BJT	TO-92	E B C	2N3906 (PNP pair)	V _{ce0} =40V, I _c =200mA, hFE~100-300	Most popular general-purpose NPN. Good for audio & switching.

Part No.	Type	Pkg	Pinout (L→R)	Complement / Alt	Key Specs	Notes
2N3906	PNP BJT	TO-92	E B C	2N3904 (NPN pair)	V _{ceo} =40V, I _c =200mA, h _{FE} ~100-300	Complementary pair to 2N3904. Identical pinout.
BC547	NPN BJT	TO-92	C B E	BC557 (PNP pair)	V _{ceo} =45V, I _c =100mA, h _{FE} ~110-800	European standard. CBE order — opposite to 2N3904! Not pin-compatible.
BC557	PNP BJT	TO-92	C B E	BC547 (NPN pair)	V _{ceo} =45V, I _c =100mA, h _{FE} ~125-800	Complementary to BC547. Same CBE pinout.
S8050	NPN BJT	TO-92	E B C	S8550 (PNP pair)	V _{ceo} =25V, I _c =1.5A, h _{FE} ~40-400	Higher current than 2N3904. Good for relay/LED array driving.
S8550	PNP BJT	TO-92	E B C	S8050 (NPN pair)	V _{ceo} =25V, I _c =1.5A, h _{FE} ~40-400	Complementary to S8050. Popular in Chinese designs.
2N5551	NPN BJT	TO-92	E B C	2N5401 (PNP pair)	V _{ceo} =160V, I _c =600mA, h _{FE} ~80-250	High-voltage NPN. Used in CRT circuits & line drivers.
2N7000	N-MOSFET	TO-92	S G D	BS170	V _{gs(th)} =0.8–3V, I _d =200mA	Logic-level N-MOS in TO-92. Good for 3.3V/5V logic switching.
BS170	N-MOSFET	TO-92	S G D	2N7000	V _{ds} =60V, I _d =500mA, V _{gs(th)} ~0.8V	60V gate rating. Common in signal switching and low-power loads.
IRFZ44N	N-MOSFET	TO-220	G D S	IRF3205	V _{ds} =55V, I _d =49A, R _{ds(on)} =17.5mΩ	Logic-level gate (V _{gs(th)} ~2–4V). Ideal for PWM motor control.
IRF540N	N-MOSFET	TO-220	G D S	IRFZ44N	V _{ds} =100V, I _d =33A, R _{ds(on)} =44mΩ	Higher voltage variant. Heatsink tab = Drain.
TIP122	NPN Darl.	TO-220	B C E	TIP127 (PNP pair)	V _{ceo} =100V, I _c =5A, h _{FE} >1000	Darlington NPN. Base-Collector-Emitter order. V _{ce(sat)} ~1.4V at 3A.
TIP127	PNP Darl.	TO-220	B C E	TIP122 (NPN pair)	V _{ceo} =100V, I _c =5A, h _{FE} >1000	Complementary Darlington to TIP122. Same BCE pinout.

* **Pinout incompatibility warning:** BC547 (C-B-E) and 2N3904 (E-B-C) are NOT pin-compatible despite being functionally similar. Direct substitution without re-routing will reverse E and C, destroying the transistor or causing circuit malfunction.

3. Multimeter Identification Method

Use your multimeter's diode-test mode (diode symbol or beep icon). This method works reliably for BJTs. MOSFETs require a different approach (see Section 3.2).

3.1 BJT Identification — 3-Step Procedure

1. Step 1 — Find the Base

- Set multimeter to diode mode.
- Touch the red probe to one pin; touch the black probe to each of the other two pins in turn.
- If both readings show 0.55 V–0.75 V, the red probe is on the Base of an NPN transistor.

- If both readings show 0.55 V–0.75 V with the BLACK probe on that pin, it is the Base of a PNP transistor.
 - If no single pin gives two valid readings, the device may be a MOSFET or is damaged.
2. **Step 2 — Distinguish Collector from Emitter**
 - For an NPN: keep the red probe on the Base. Measure the remaining two pins with the black probe.
 - Both readings will be in the 0.55–0.75 V range. The pin with the slightly HIGHER reading (~2–10 mV more) is the Collector (C); the lower-reading pin is the Emitter (E).
 - This small difference arises from the asymmetric doping profile of the BJT structure — it is a reliable test but the difference can be subtle. If unsure, consult the datasheet.
 3. **Step 3 — Confirm Polarity**

Observation	Conclusion	Memory Aid
Red probe on Base: both other pins read 0.55–0.75 V	NPN transistor	Red (+) on Base → NPN (current flows into Base to turn ON)
Black probe on Base: both other pins read 0.55–0.75 V	PNP transistor	Black (–) on Base → PNP (current flows out of Base to turn ON)
All pin combinations show OL or near zero	Possible MOSFET or damaged device	Use MOSFET test method (Section 3.2)

3.2 MOSFET Identification

MOSFETs have an insulated gate — the diode test cannot forward-bias G directly. Use this sequence instead:

- Identify the two lower-resistance pins by measuring D-S: a body diode exists between Drain and Source (forward-biased from S to D on N-MOS, D to S on P-MOS).
- Confirm the Gate by elimination — the remaining pin. G-to-S and G-to-D should both show OL (open) on diode mode. Any measurable reading indicates a damaged gate oxide.
- To verify enhancement-mode N-MOS operation: touch G with your finger (static charge builds V_{gs}), then immediately probe D-S — the channel should now conduct (low resistance). Short G to S to discharge.
- Caution: The finger-static method applies only to enhancement-mode devices. Do not attempt on depletion-mode types.

4. Assembly Best Practices

4.1 Mirror-Image (Board-View) Error

One of the most frequent assembly mistakes: when soldering from the BOTTOM of the PCB, all pin orders are horizontally mirrored compared to the top-view datasheet diagram.

Top View (Component Side)	Bottom View (Solder Side) — MIRRORED!
BC547 TO-92: C — B — E (left to right)	Soldering from bottom: E — B — C (left to right)
IRFZ44N TO-220: G — D — S (left to right)	Soldering from bottom: S — D — G (left to right)

Rule: Always read the datasheet orientation as viewed from the top (component side). Flip your reference mentally — or mark E/B/C directly on the PCB silkscreen rather than using generic 1/2/3 numbers.

4.2 PCB Design Recommendations

- Label each pad by function (E, B, C or G, D, S) on the silkscreen, not just by pin number.
- Draw the TO-92 flat-face outline on the silkscreen to indicate device orientation unambiguously.
- Mark Pin 1 on SOT-23 footprints with a triangle or dot on copper or silkscreen.

- TO-220 heatsink tab is electrically live (usually Drain or Collector). Always use an insulating mica or Kapton pad + nylon bushing when mounting to a metal chassis.
- Add a 10–100 Ohm gate/base resistor in series to suppress ringing and provide ESD protection without significantly slowing switching speed.
- Place a freewheeling diode across any inductive load (relay, motor) switched by a transistor. 1N4148 for signal relays; 1N4007 or Schottky (e.g. 1N5819) for power loads.

4.3 ESD (Electrostatic Discharge) Protection

- MOSFETs are highly susceptible to ESD — gate oxide can rupture at voltages as low as 20 V. Wear an anti-static wrist strap connected to ground when handling bare devices.
- Store MOSFETs with leads shorted together using conductive foam or aluminum foil until ready to solder.
- Use a temperature-controlled, grounded-tip soldering iron. Keep soldering time under 3 seconds per joint. Recommended tip temperature: 300–350 degrees C.
- BJTs are more robust but can still be damaged by ESD in high-frequency or low-noise circuits. The same handling precautions are good practice.

5. Application Selection Guide

Use this table to quickly match a design requirement to the right transistor family and part.

Application	Recommended Part	Design Notes
LED / small load switch (<100 mA)	2N3904 / BC547	$R_b = (V_{in} - 0.7 V) / I_b$. Use $h_{FE} = 50$ for conservative I_b . Add 1 k Ω base resistor minimum.
Relay driver	S8050 / TIP122	Freewheeling diode (1N4148 or 1N4007) mandatory across relay coil to suppress back-EMF spike.
Low-noise audio preamp	2N5551 / BC549C	Bias collector at $\sim V_{cc}/2$. Add emitter degeneration resistor (100–470 Ω) for thermal stability.
Logic-level shifting (5 V \leftrightarrow 3.3 V)	2N7000 / BSS138	BSS138 + pull-up resistors on both sides gives bidirectional shifting without extra ICs.
Motor / high-current control (>10 A)	IRFZ44N / IRF3205	H-bridge needs 4 FETs. Enforce dead-time (>100 ns) between high/low-side switching to prevent shoot-through.
PWM dimming / speed control	Any N-MOSFET	Switching frequency >20 kHz eliminates audible noise. Verify gate charge vs. driver current capability.
Complementary push-pull output	2N3904 + 2N3906	Insert diodes (1N4148) in series with bases or bias V_{be} to eliminate crossover distortion.

All pinout data compiled from official manufacturer datasheets (ON Semiconductor, Fairchild/onsemi, Vishay, International Rectifier). Verify against the specific revision of the datasheet for your exact part lot. This document is intended as a quick-reference aid; it does not substitute for the full datasheet during design review.

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